

PRODUCT CHANGE NOTIFICATION

Date Issued: December 7, 2018

Product Identification: Bel SI-6xxxx-F Series ICMs

PCN Number: PC4180098

Reason for Change (s): In an effort to continually improve our product, Bel is pleased to announce an upgrade to the assembly process for the SI-6xxxx-F 10/100BaseT product series of ICM part numbers. This PCN covers 2 related changes. First, due to environmental policy changes now and in the future, the varnish coating over the magnetics components can no longer be used. Bel is transitioning to a silicone potting compound consistent with the remainder of the Bel ICM product line. Second, to reduce the solder joints present in the process, the former mounting board is being replaced by a traditional printed circuit board consistent with the remainder of the Bel ICM product line. The affected part numbers are:

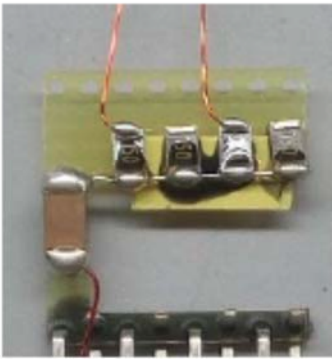
SI-60001-F	SI-60136-F	SI-60089-F	SI-60195-F
SI-60002-F	SI-60144-F	SI-60104-F	SI-60208-F
SI-60005-F	SI-60146-F	SI-60105-F	SI-60213-F
SI-60008-F	SI-60152-F	SI-60110-F	SI-60233-F
SI-60015-F	SI-60153-F	SI-60114-F	SI-60238-F
SI-60022-F	SI-60158-F	SI-60115-F	SI-60252-F
SI-60024-F	SI-60160-F	SI-60116-F	SI-60264-F-A
SI-60029-F	SI-60162-F	SI-30107-F	SI-60266-F
SI-60053-F	SI-60163-F	SI-60118-F	SI-61001-F
SI-60054-F	SI-60182-F	SI-60123-F	SI-61002-F
SI-60062-F	SI-60182-F-R	SI-60126-F	SI-62003-F
SI-60076-F	SI-60192-F	SI-60128-F	SI-62006-F
	SI-60193-F	SI-60135-F	

These changes will not affect “form, fit, or function”, nor do they affect any other dimensions or electrical parameters of the part. No other related changes to the above series are being implemented at this time.

Description of the Change (s): First, the varnish coating over the magnetics components is transitioning to a silicone potting compound consistent with the remainder of the Bel ICM product line. Second, to reduce the solder joints present in the process, the former mounting board is being replaced by a traditional printed circuit board consistent with the remainder of the Bel ICM product line.

WAS

1. Mounting board: manual solder the components onto mounting board

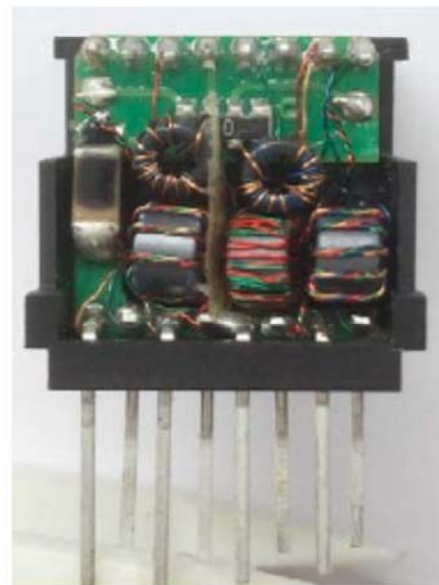
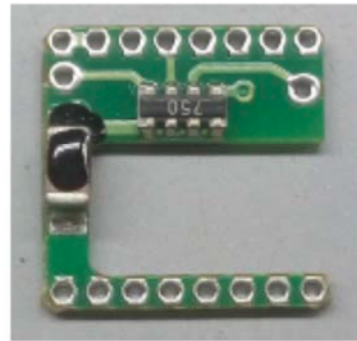


2. Wire connection and dressing:



IS

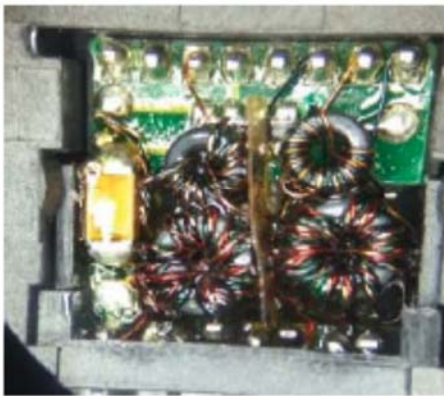
PCBA: P&P the components onto PCB by SMT process



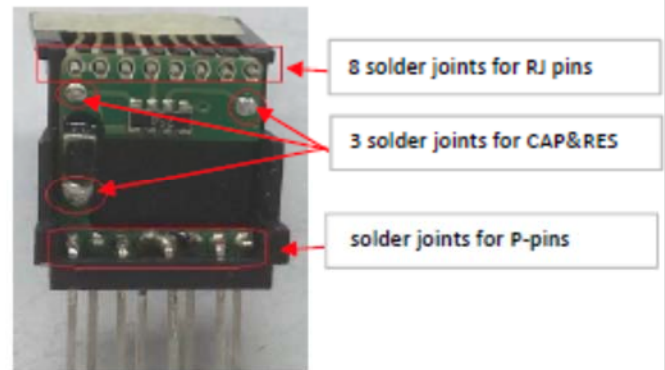
3. manual solder joints:



4. Apply varnish to cover the coils



manual solder joints:



Apply silicone to cover the coils



5. FG outline: the outline is the same.



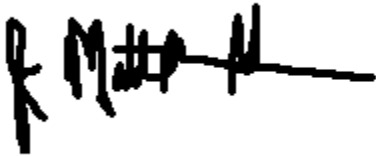
Planned Timing and Implementation of Change: This change will be implemented on any new orders after March 31st, 2019.

Impact on Quality and Reliability: Some improvement over existing process.

Availability of Qualification Data: Upon Request.

Remarks: None.

Signature: John Hess, ICM Product Manager

A handwritten signature in black ink, appearing to read 'J. Hess', with a long horizontal line extending to the right.

(Bel Representative)

Note: This form should only be used for advising the customer.